TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIV)

2SK3564

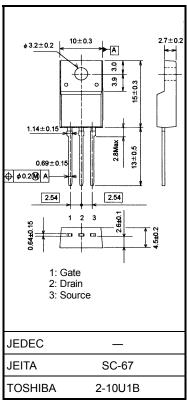
Switching Regulator Applications

Unit: mm

- Low drain-source ON resistance: RDS (ON) = 3.7Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 2.6 \text{ S (typ.)}$
- Low leakage current: IDSS = 100 $\,\mu$ A (VDS = 720 V)
- Enhancement mode: $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	900	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	3	А	
	Pulse (t = 1 ms) (Note 1)	I _{DP}	9		
Drain power dissipation (Tc = 25°C)		PD	40	W	
Single pulse avalanche energy (Note 2)		E _{AS}	408	mJ	
Avalanche current		I _{AR}	3	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	4.0	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

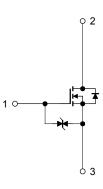
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W



Note 2:
$$V_{DD} = 90 \text{ V}$$
, $T_{ch} = 25^{\circ}\text{C}$, $L = 83 \text{ mH}$, $I_{AR} = 3.0 \text{ A}$, $R_G = 25 \Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.





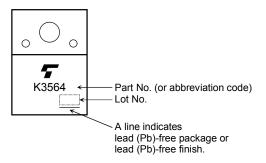
Electrical Characteristics (Ta = 25°C)

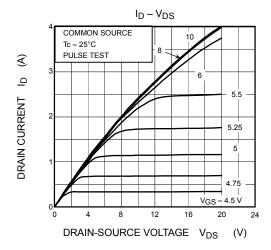
Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source brea	akdown voltage	V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30	_	_	V
Drain cut-off curr	ent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	900	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 1.5 A	_	3.7	4.3	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 20 V, I _D = 1.5 A	0.65	2.6	_	S
Input capacitance		C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	700	_	pF
Reverse transfer capacitance		C _{rss}		_	15	_	
Output capacitance		Coss			75	_	
Switching time	Rise time	t _r	V_{GS} $V_{D} = 1.5 \text{ A } V_{OUT}$ V_{GS} $V_{D} \approx 200 \text{ V}$		20	_	
	Turn-on time	t _{on}			60	_	20
	Fall time	t _f			35	_	ns
	Turn-off time	t _{off}	Duty ≦ 1%, t _w = 10 μs	_	125	_	
Total gate charge		Qg		_	17	_	
Gate-source charge		Qgs	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$	_	10	_	nC
Gate-drain charge		Q _{gd}		_	7	_	

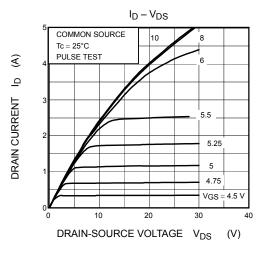
Source-Drain Ratings and Characteristics (Ta = 25°C)

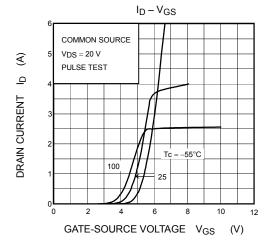
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	3	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	9	Α
Forward voltage (diode)	V _{DSF}	$I_{DR} = 3 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.9	V
Reverse recovery time	t _{rr}	$I_{DR} = 3 \text{ A}, V_{GS} = 0 \text{ V},$	_	850	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs	_	4.7	_	μС

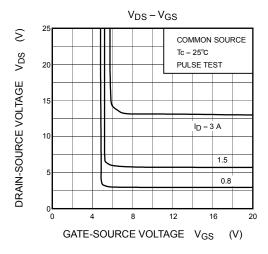
Marking

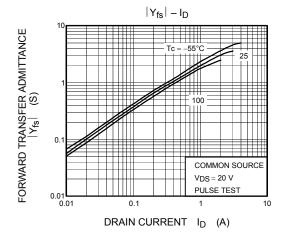


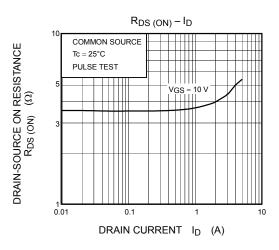


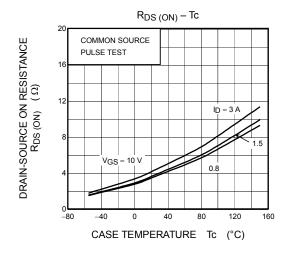


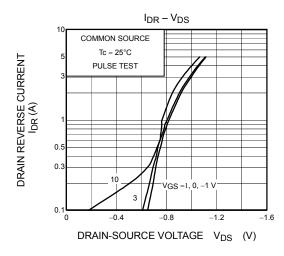


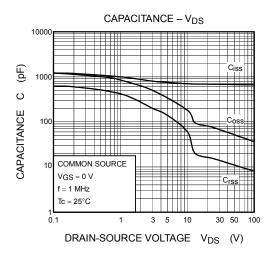


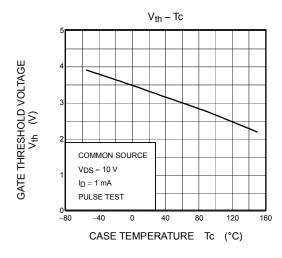


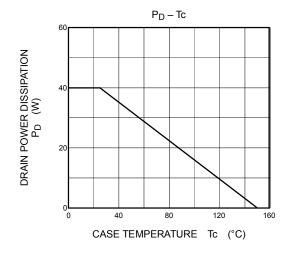


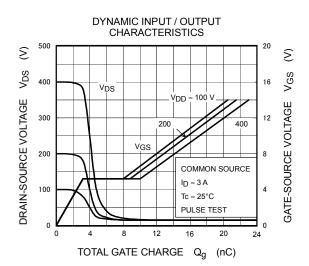




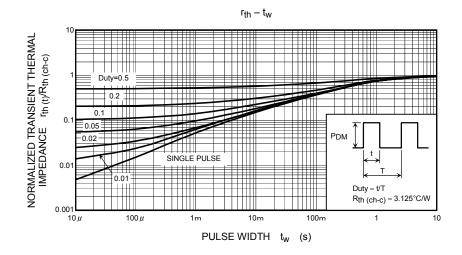


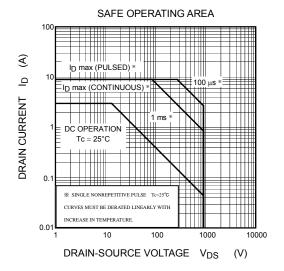


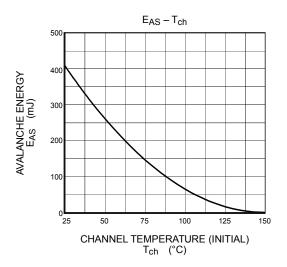


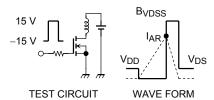


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$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V, } L = 83\text{mH}$

$$\mathsf{EAS} = \frac{1}{2} \cdot L \cdot l^2 \cdot \left(\frac{\mathsf{BVDSS}}{\mathsf{BVDSS} - \mathsf{VDD}} \right)$$

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